

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ESD103-B1-02ELS E6327	**Issued**	29. August 2013
MA#	MA001100018		
Package	PG-TSSLP-2-4	**Weight***	0.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3268	
	noble metal	gold	7440-57-5	0.003	1.27		12681	
	inorganic material	silicon	7440-21-3	0.020	9.40	11.00	93964	109913
leadframe	non noble metal	nickel	7440-02-0	0.108	50.67	50.67	506732	506732
wire	noble metal	gold	7440-57-5	0.003	1.29	1.29	12949	12949
encapsulation	organic material	carbon black	1333-86-4	0.000	0.16		1641	
	plastics	epoxy resin	-	0.010	4.75		47537	
	inorganic material	silicondioxide	60676-86-0	0.059	27.87	32.78	278660	327838
leadfinish	noble metal	gold	7440-57-5	0.004	1.73	1.73	17290	17290
plating	noble metal	palladium	7440-05-3	0.001	0.60		5996	
	noble metal	gold	7440-57-5	0.004	1.93	2.53	19282	25278
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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